

REMARKS

In response to the office action of April 29, 2009, applicant submits the following comments. Claims 14, 18, 19 and 25 are amended. Claims 31-33 are new. The new claims are supported at least by FIG. 1F. Claims 16-17 and 21-22 are canceled. Applicant respectfully reserves the right to pursue any canceled subject matter in one or more continuing applications. Applicant requests reconsideration in view of the amendments and the foregoing remarks.

Section 103 Rejections

Claims 14, 16, 18-21, 25-27 and 30 were rejected as being unpatentable over U.S. 6,468,439 ("Whitehurst").

Claim 17 was objected to as being dependent upon a rejected base claim, but was found to be allowable if rewritten in independent form. Applicant has amended claim 14 to incorporate the subject matter of claims 16 and 17. Therefore, applicant believes that claim 14 and the claims that depend therefrom are in condition for allowance.

Claim 25 has been amended. Claim 25 now describes an electrical component with a substrate having a main surface with a first structure and second structure arranged thereon, wherein the first structure possesses a cross section which widens towards the substrate and in a direction perpendicular to the main surface of the substrate has a geometric form with a perimeter that has recessed areas deviating from the geometric form. The first structure consists of a bond pad and the second structure consists of contact lines.

Whitehurst describes a device with a stack of etched metal layers (col. 1, lines 7-20). The a ground plane 22 supports a first etched metal layer 24, a second etched metal layer 26 and a third etched metal layer 28 (FIG. 2, col. 17, lines 46-67). The three metal layers 24, 26, 28 are in contact with one another in a direction vertical to the surface of the ground plane 22.

Whitehurst does not describe a first structure that consists of a bond pad and a second structure consists of contact lines. Rather, Whitehurst describes structures that are stacked vertically on one another. A person of skill in the art would not arrange a bond pad and contact lines vertically on one another. Rather, if a device with bond pads or conductive lines were

formed with multiple layers of conductive layers material stacked vertically on one another, all of the vertically stacked layers would be considered to be either the bond pad or the conductive lines. For at least this reason, claim 25 as amended is not unpatentable over Whitehurst.

New Claims

New claims 31-33 depends from claim 25 and is not unpatentable over Whitehurst for at least the same reason as provided above with respect to claim 25.

Allowed Claims

Applicant thanks the Examiner for finding claims 1, 3-13, 28 and 29 in condition for allowance.

Please apply any required charges or credits to deposit account 06-1050.

Respectfully submitted,

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